

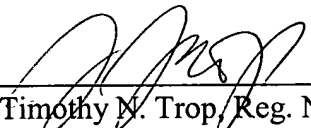
## REMARKS

The cited reference at the cited location applies 2 pounds per square inch. By reducing the pressure, the low down force limits the polish rate and helps to prevent damage to the wafer surface and enhances the life of the polishing pad. Support for the added limitation may be found at page 4 of the specification, line 17.

In view of these remarks, the application is now in condition for allowance and the Examiner's prompt action in accordance therewith is respectfully requested.

Respectfully submitted,

Date: May 5, 2005



---

Timothy M. Trop, Reg. No. 28,994  
TROP, PRUNER & HU, P.C.  
8554 Katy Freeway, Ste. 100  
Houston, TX 77024  
713/468-8880 [Phone]  
713/468-8883 [Fax]

Attorneys for Intel Corporation